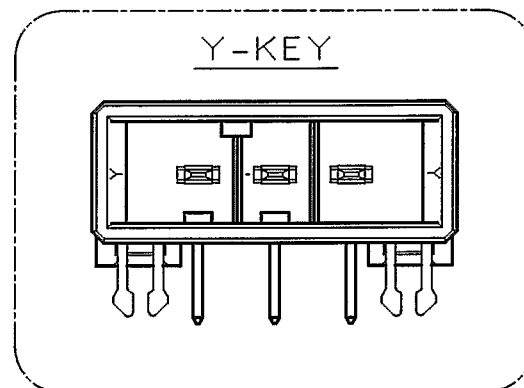
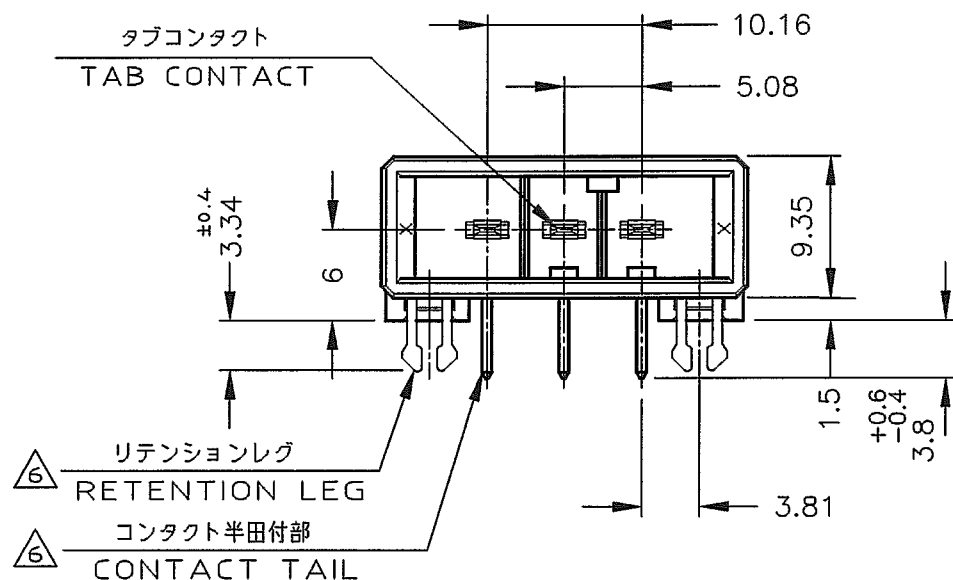
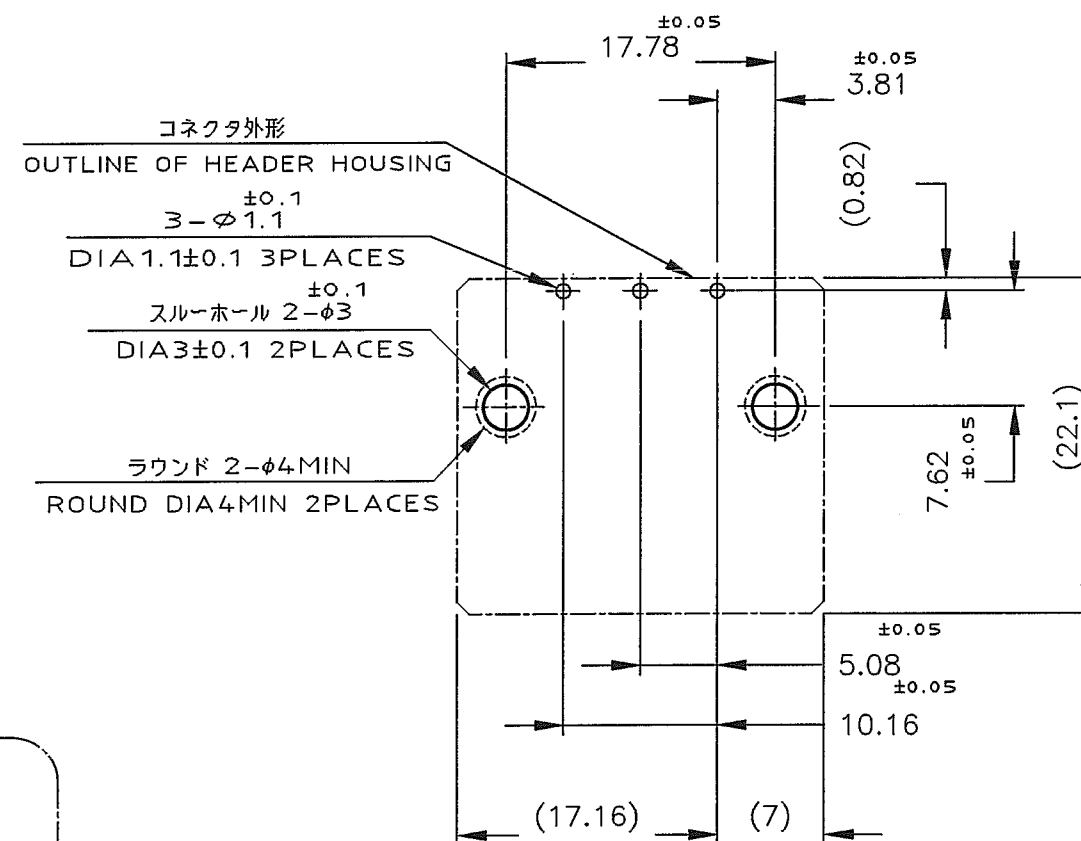
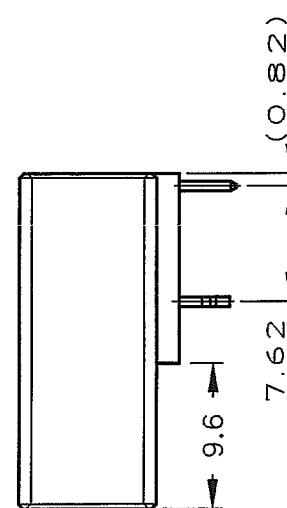
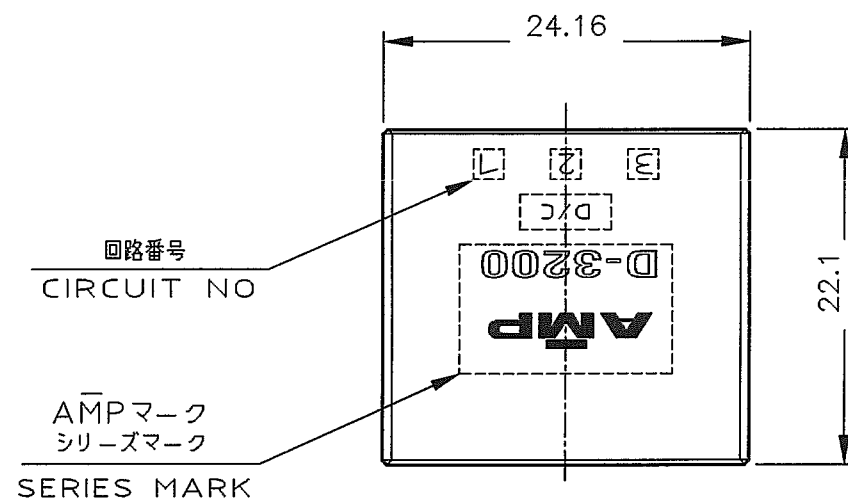




推奨基板取付け寸法
PC 基板厚: 1.6±0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN
PC BOARD THICKNESS: 1.6±0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

- NOTES
- MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER
CONTACT: COPPER ALLOY
RETENTION LEG: COPPER ALLOY
 - FINISH (CONTACT AREA): 0.38μm PdNi & Au PLATING OVER NICKEL
 - FINISH (CONTACT AREA): 0.76μm PdNi & Au PLATING OVER NICKEL
 - FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
 - FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
 - FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

⑥	④	2-178138-5	Y
⑥	③	2-178138-3	Y
⑥	②	2-178138-2	Y
⑥	④	1-178138-5	X
⑥	③	1-178138-3	X
⑥	②	1-178138-2	X
(FINISH)	製品番号 (PART NO.)	KEY	

F	REVISED PER ECR-25-250788	F.Z	R.B	16 JAN 2025
E1	REVISED PER ECO-11-005030	RK	HMR	23 MAR 11
LTR	REVISION RECORD	DR	CHK	DATE

WIRE RANGE		INSULATION DIA	NAME
mm ² (AWG -)		mmφ	
MATERIAL		FINISH	
SEE NOTE 注記参照		SEE NOTE 注記参照	
DR.	20/MAR/'95	DE.	20/MAR/'95
K.IKEDA		K.IKEDA	
CHK.	23/MAR/'95	APP.	23/MAR/'95
S.MANABE		S.MANABE	
3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200			
一般公差 (GENERAL TOLERANCE)			
10mmF	±0.3	SIZE	A3
10mmB	±0.4	LOC	J
30mmA100mmF	±0.5	NUMBER	C-178138
角 度	±3°	SCALE	2-1
		REV.	F
		SHEET	1 OF 1